

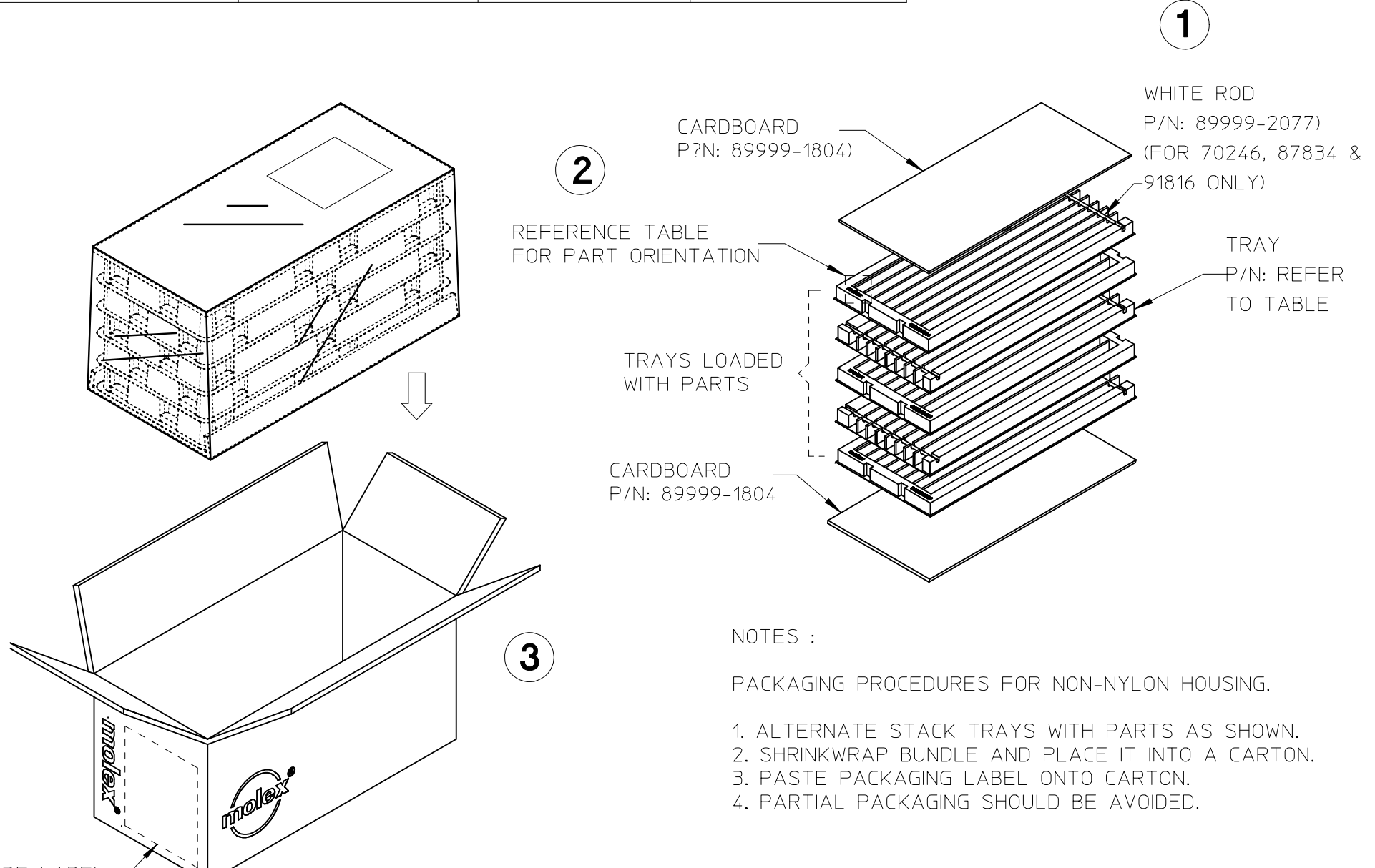
Molex 70247-0851 PDF

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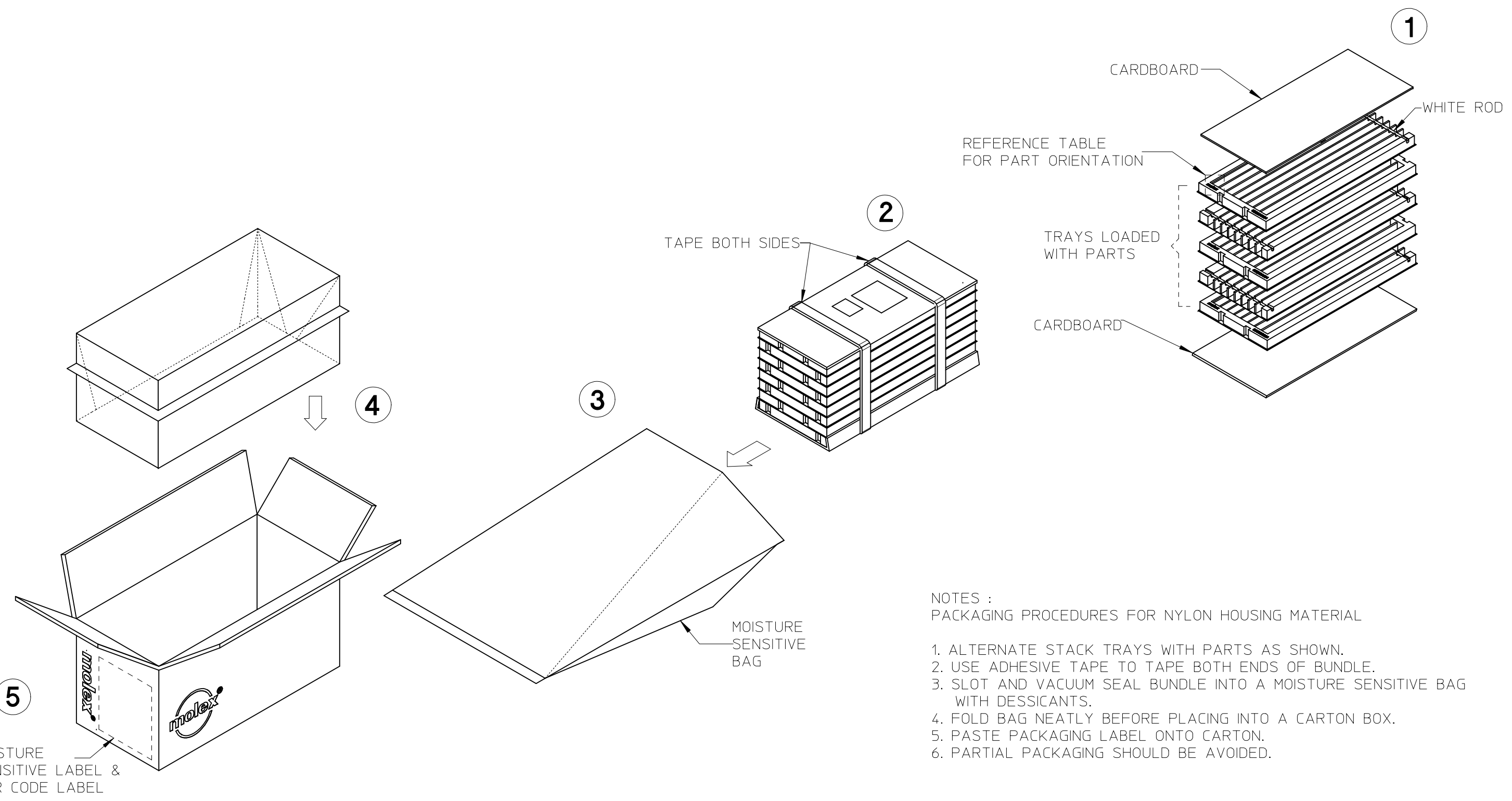
CKT SIZE	RIGHT ANGLE VERSION		THROUGH HOLE VERSION	
	QTY/ TRAY	8 TRAYS/ CARTON	QTY/ TRAY	10 TRAYS/ CARTON
4	200	1600	200	2000
6	168	1344	168	1680
8	144	1152	144	1440
10	128	1024	120	1200
12	112	896	112	1120
14	96	768	96	960
16	88	704	88	880
18	80	640	80	800
20	72	576	72	720
24	64	512	64	640
26	64	512	56	560
30	56	448	56	560
32	48	384	48	480
34	48	384	48	480
36	48	384	48	480
40	40	320	40	400
44	40	320	40	400
48	32	256	32	320
50	32	256	32	320
56	32	256	32	320
60	24	192	24	240
64	24	192	24	240
72	24	192	24	240

SERIES	TRAY P/N	ORIENTATION OF PART IN TRAY	
70247/ 87835 RIGHT ANGLE	89990-8054		
70246/ 87834 / 91816 THROUGH HOLE	89990-8056/ 89990-8057		



- NOTES :
- ALTERNATE STACK TRAYS WITH PARTS AS SHOWN.
 - SHRINKWRAP BUNDLE AND PLACE IT INTO A CARTON.
 - PASTE PACKAGING LABEL ONTO CARTON.
 - PARTIAL PACKAGING SHOULD BE AVOIDED.

ENTER DESCRIPTION EC NO: S2017-0407 DRWN:FCS00 CHKD:CG0H APPR:KHL IM 2017/01/25 2017/02/03 2017/02/07	QUALITY SYMBOLS 	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:2	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
								TITLE PACKAGING SPECIFICATION FOR C-GRID SERIES		
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± --- 0 PLACE ± --- ± ---		DRAWN BY ATSEE CHECKED BY SKANG APPROVED BY MLONG DATE 2009/05/20 DATE 2009/07/02 DATE 2009/07/08		MATERIAL NO. SEE TABLE		DOCUMENT NO. PK-87835-001		SHEET NO. 1 OF 2
		ANGULAR ± 3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



- NOTES :
- PACKAGING PROCEDURES FOR NYLON HOUSING MATERIAL
1. ALTERNATE STACK TRAYS WITH PARTS AS SHOWN.
 2. USE ADHESIVE TAPE TO TAPE BOTH ENDS OF BUNDLE.
 3. SLOT AND VACUUM SEAL BUNDLE INTO A MOISTURE SENSITIVE BAG WITH DESSICANTS.
 4. FOLD BAG NEATLY BEFORE PLACING INTO A CARTON BOX.
 5. PASTE PACKAGING LABEL ONTO CARTON.
 6. PARTIAL PACKAGING SHOULD BE AVOIDED.

ENTER DESCRIPTION EC NO: S2017-0407 DRWN:FCS00 CHKD:CGOH APPR:KHLIM	2017/01/23 2017/02/03 2017/02/07	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		$\nabla_A = 0$ $\nabla_C = 0$ $\nabla_P = 0$	mm	INCH	DRAWN BY ATSEE	DATE 2009/05/20	TITLE PACKAGING SPECIFICATION FOR C-GRID SERIES				
			4 PLACES	± ---	± ---	CHECKED BY SKANG	DATE 2009/07/02				
			3 PLACES	± ---	± ---	APPROVED BY MLONG	DATE 2009/07/08				
			2 PLACES	± 0.20	± ---						
	1 PLACE	± ---	± ---	MATERIAL NO. SEE TABLE		DOCUMENT NO. PK-87835-001		SHEET NO. 2 OF 2			
	0 PLACE	± ---	± ---	ANGULAR ± 3 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3								



PRODUCT SPECIFICATION

C-GRID SHROUDED WAFER

1.0 SCOPE

This specification covers a dual row wafer (header) system on .100 grid. The wafer body has a low profile shroud with a window(s) or open slot(s) to accommodate connector bodies with passive latching ramps. It is designed for P. C. Board mounting and subsequent mating to box contact type connectors

2.0 PRODUCT DESCRIPTION

2.1 Product covered by this specification is for series number 70246, 70247, 71384, 87054, 87256, 87257, 87556, 87834 and 87835

2.2 For dimensions, materials & plating, refer to the appropriate product drawings.

3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

The following documents are part of this specification to the extent specified herewith. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and reference documents, this specification shall take the precedence.

MIL-STD-202 Test Methods for Electrical and Electronic Component Parts.

MIL-STD-1344 Test methods of Electrical Connector

4.0 RATINGS

4.1 Voltage : 250 Volts DC Maximum

4.2 Current : 2.5 Amp DC Min

4.3 Operating Temperature : -55°C to +120°C

REVISION: H2	ECR/ECN INFORMATION: EC No: S2006-0380 DATE: 2005/09/23	TITLE: C-GRID SHROUDED WAFER	SHEET No. 1 of 3
DOCUMENT NUMBER: PS-70246-100	CREATED / REVISED BY: YLQIAO 2005/09/23	CHECKED BY: BOKOK 2005/09/27	APPROVED BY: PTLIM 2005/09/27



PRODUCT SPECIFICATION

5.0 PERFORMANCE

5.1 ELECTRICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
1	Insulation Resistance	Measurements taken between adjacent contacts where 500VDC is applied. (MIL-STD-202F, Method 302)	12000 Megaohms Minimum
2	Dielectric Strength	Mated samples subjected to 900 VAC rms for 1 min. between adjacent contacts. (MIL-STD-202F, Method 301)	No breakdown
3	Current Rating	Steady state DC voltage source is supplied for 96 hours with a 30 degree C Max. temperature rise over ambient	2.5 amp (D.C.) Maximum

5.2 MECHANICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
4	Contact Retention	Apply axial load at a rate of 0.5 inch/ (12.7mm) minimum up to maximum required load. (MIL-STD-1344A, Method 2007.1)	2 lb / 0.91kgf (Minimum) Initial 0.88 lb / 0.40kgf (Minimum) After resistance to solder heat

REVISION:	ECR/ECN INFORMATION:	TITLE:	SHEET No.
H2	EC No: S2006-0380 DATE: 2005/09/23	C-GRID SHROUDED WAFER	2 of 3
DOCUMENT NUMBER:	CREATED / REVISED BY:	CHECKED BY:	APPROVED BY:
PS-70246-100	YLQIAO 2005/09/23	BOKOK 2005/09/27	PTLIM 2005/09/27



PRODUCT SPECIFICATION

5.3 ENVIRONMENTAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
5	Resistance to Soldering Heat (Wave Soldering) For Series: 87256, 87257, 87834, 87835, 70246, 70247 87556	Sample mounted on PCB and subject to wave soldering as per MIL-STD-202G, method 210F, Condition B For series using a) Nylon 4/6 plastic material Temperature : 260 ±5°C for 5sec b) PBT / PET plastic material Temperature : 230 ±5°C for 3sec	No damage in appearance of the connector
6	Resistance to Soldering Heat (Reflow) For Series: 71384, 87054	1. <u>Preheat</u> : Increase in temperature < 4°C /sec 2. <u>Soldering</u> : Maximum Reflow temperature < 230°C 3. <u>Cool Down</u> : Cool temperature < 4°C /sec	No damage in appearance of the connector
7	Solderability	Solder tail to be dipped in flux as per MIL-STD-202F, method 208	Soldertail should have 95% continuous new solder coating coverage (Apply to non-kinked Soldertail only)

6.0 PACKAGING

Product shall be packaged and protected against damage during handling, transportation and storage.

REVISION: H2	ECR/ECN INFORMATION: EC No: S2006-0380 DATE: 2005/09/23	TITLE: C-GRID SHROUDED WAFER	SHEET No. 3 of 3
DOCUMENT NUMBER: PS-70246-100	CREATED / REVISED BY: YLQIAO 2005/09/23	CHECKED BY: BOKOK 2005/09/27	APPROVED BY: PTLIM 2005/09/27